

# RCD060N25

## Nch 250V 6A Power MOSFET

$V_{DSS}$	250V
R <sub>DS(on)</sub> (Max.)	$530$ m $\Omega$
I <sub>D</sub>	6A
$P_D$	52W

## ● Features

- 1) Low on-resistance.
- 2) Fast switching speed.
- 3) Drive circuits can be simple.
- 4) Parallel use is easy.
- 5) Pb-free lead plating; RoHS compliant
- 6) 100% Avalanche tested

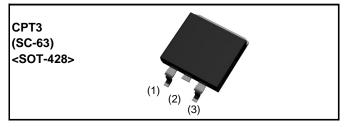
## Application

**Switching Power Supply** 

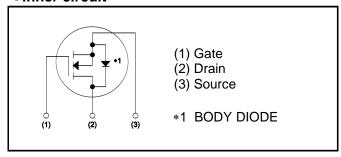
**Automotive Motor Drive** 

Automotive Solenoid Drive

#### Outline



## •Inner circuit



Packaging specifications

	Packaging	Taping
Reel size (	Reel size (mm)	330
Tuno	Tape width (mm)	16
Type	Basic ordering unit (pcs)	2,500
	Taping code	TL
	Marking	C06N25

## ● Absolute maximum ratings (T<sub>a</sub> = 25°C)

Parameter	Symbol	Value	Unit	
Drain - Source voltage	$V_{DSS}$	250	V	
Continuous drain current	T <sub>c</sub> = 25°C	I <sub>D</sub> *1	±6	А
Continuous drain current	T <sub>c</sub> = 100°C	I <sub>D</sub> *1	±3.3	А
Pulsed drain current	I <sub>D,pulse</sub> *2	±24	А	
Gate - Source voltage	$V_{GSS}$	±30	V	
Avalanche energy, single pulse	E <sub>AS</sub> *3	2.62	mJ	
Avalanche current		I <sub>AS</sub> *3	3	А
$T_c = 25^{\circ}C$		P <sub>D</sub>	52	W
Power dissipation $T_a = 25^{\circ}C^{*4}$		P <sub>D</sub>	0.85	W
Junction temperature	T <sub>j</sub>	150	°C	
Range of storage temperature	T <sub>stg</sub>	-55 to +150	°C	

## ●Thermal resistance

Parameter	Symbol	Values			Unit
- Farameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	$R_{thJC}$	-	-	2.36	°C/W
Thermal resistance, junction - ambient *4	$R_{thJA}$	-	-	147	°C/W
Soldering temperature, wavesoldering for 10s	T <sub>sold</sub>	-	-	265	°C

# ●Electrical characteristics (T<sub>a</sub> = 25°C)

Parameter	Symbol	Conditions		Values	Unit	
raiametei	Symbol Conditions		Min.	Тур.	Max.	Offic
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V$ , $I_D = 1mA$	250	-	-	V
		$V_{DS} = 250V, V_{GS} = 0V$			10	
Zero gate voltage	l	$T_j = 25^{\circ}C$	_	1	10	μА
drain current	I <sub>DSS</sub>	$V_{DS} = 250V, V_{GS} = 0V$		-	100	
		T <sub>j</sub> = 125°C	-			
Gate - Source leakage current	I <sub>GSS</sub>	$V_{GS} = \pm 30V, V_{DS} = 0V$	-	-	±100	nA
Gate threshold voltage	V <sub>GS (th)</sub>	$V_{DS} = 10V$ , $I_D = 1mA$	3.0	-	5.0	V
		$V_{GS} = 10V, I_D = 3.0A$	-	410	530	
Static drain - source on - state resistance	R <sub>DS(on)</sub> *5	$V_{GS} = 10V, I_D = 3.0A$		020	1200	mΩ
		T <sub>j</sub> = 125°C	-	- 930		
Forward transfer admittance	g <sub>fs</sub>	$V_{DS} = 10V, I_{D} = 3.0A$	2.2	4.4	-	S

# ●Electrical characteristics (T<sub>a</sub> = 25°C)

Parameter	Symbol	Conditions	Values			Unit
Parameter	Symbol	Min		Тур.	Max.	Offic
Input capacitance	C <sub>iss</sub>	$V_{GS} = 0V$	-	840	-	
Output capacitance	$C_{oss}$	V <sub>DS</sub> = 25V	-	50	-	pF
Reverse transfer capacitance	$C_{rss}$	f = 1MHz	-	25	-	
Turn - on delay time	t <sub>d(on)</sub> *5	$V_{DD} \simeq 125V, V_{GS} = 10V$	ı	22	ı	
Rise time	t <sub>r</sub> *5	$I_D = 3A$	ı	20	ı	nc
Turn - off delay time	t <sub>d(off)</sub> *5	$R_L = 41.67\Omega$	-	30	ı	ns
Fall time	t <sub>f</sub> *5	$R_G = 10\Omega$	-	13	-	

# •Gate Charge characteristics $(T_a = 25^{\circ}C)$

Parameter	Symbol	Conditions	Values			Unit	
raiametei 	Symbol	Conditions	Min.	Тур.	Max.	Offic	
Total gate charge	$Q_g^{*5}$	V <sub>DD</sub> ≃ 125V	-	15	ı		
Gate - Source charge	Q <sub>gs</sub> *5	I <sub>D</sub> = 6A	-	6	-	nC	
Gate - Drain charge	Q <sub>gd</sub> *5	V <sub>GS</sub> = 10V	-	6	-		
Gate plateau voltage	V <sub>(plateau)</sub>	$V_{DD} \simeq 125V, I_D = 6A$	-	7.5	-	V	

# ●Body diode electrical characteristics (Source-Drain)(T<sub>a</sub> = 25°C)

Parameter	Symbol Conditions			Unit		
- Farameter			Min.	Тур.	Max.	Offic
Continuous source current	I <sub>S</sub> *1	T <sub>c</sub> = 25°C	-	-	6	Α
Pulsed source current	I <sub>SM</sub> *2	1 <sub>c</sub> = 23 C	-	-	24	Α
Forward voltage	V <sub>SD</sub> *5	$V_{GS} = 0V, I_{S} = 6.0A$	-	-	1.5	V
Reverse recovery time	t <sub>rr</sub> *5	I <sub>S</sub> = 3.0A	-	85	-	ns
Reverse recovery charge	Q <sub>rr</sub> *5	di/dt = 100A/μs	-	250	-	nC

<sup>\*1</sup> Limited only by maximum temperature allowed.

<sup>\*2</sup> Pw  $\leq$  10 $\mu$ s, Duty cycle  $\leq$  1%

<sup>\*3</sup> L  $\simeq$  500 $\mu$ H, V<sub>DD</sub> = 50V, Rg = 25 $\Omega$ , starting T<sub>j</sub> = 25°C

<sup>\*4</sup> Mounted on a epoxy PCB FR4 (20mm × 30mm × 0.8mm)

<sup>\*5</sup> Pulsed

Fig.1 Power Dissipation Derating Curve

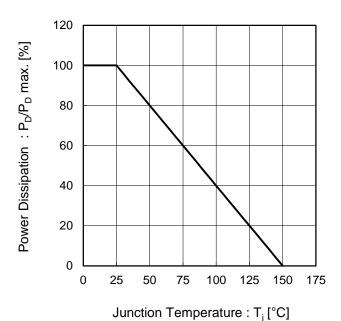
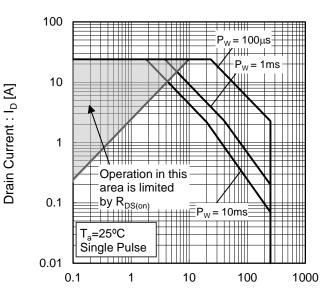
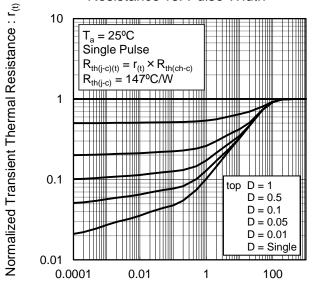


Fig.2 Maximum Safe Operating Area



Drain - Source Voltage :  $V_{DS}$  [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width



Pulse Width :  $P_W$  [s]

Fig.4 Avalanche Current vs Inductive Load

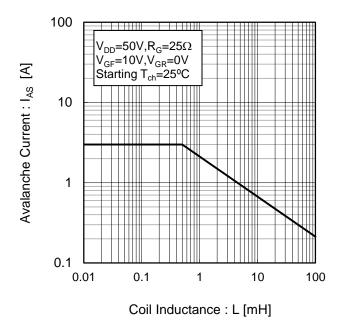


Fig.5 Avalanche Energy Derating Curve vs Junction Temperature

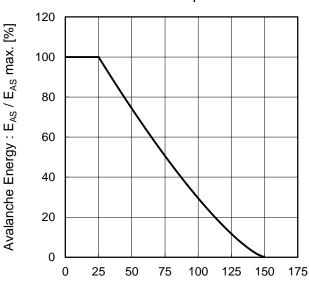


Fig.6 Typical Output Characteristics(I)

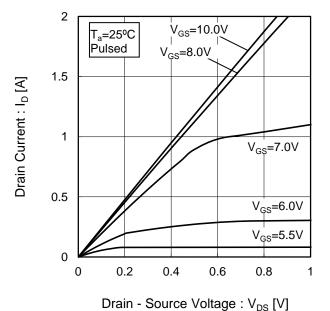
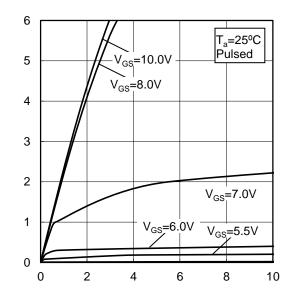


Fig.7 Typical Output Characteristics(II)

Junction Temperature : T<sub>i</sub> [°C]



Drain - Source Voltage: V<sub>DS</sub> [V]

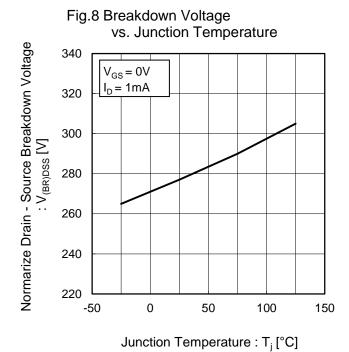
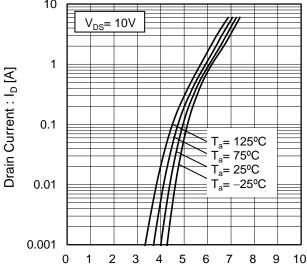


Fig.9 Typical Transfer Characteristics



Gate - Source Voltage : V<sub>GS</sub> [V]

Fig.10 Gate Threshold Voltage vs. Junction Temperature

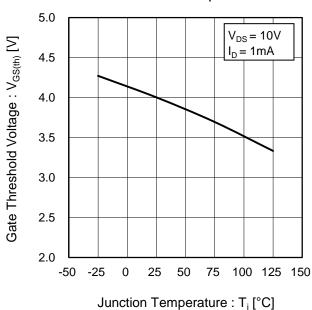
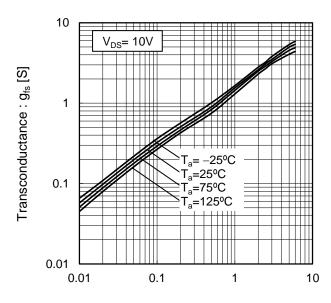


Fig.11 Transconductance vs. Drain Current



Drain Current : I<sub>D</sub> [A]

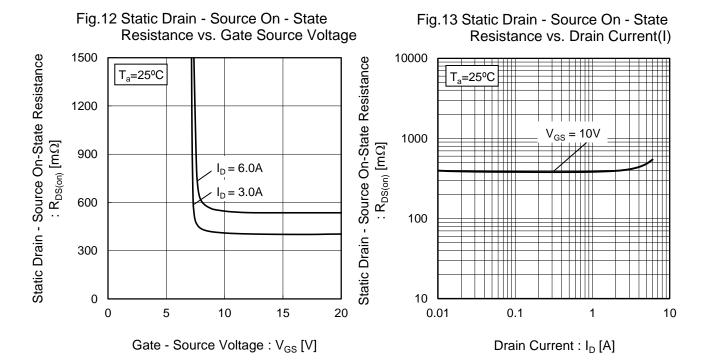
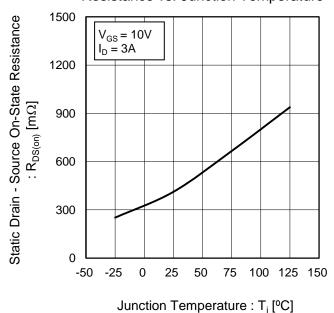


Fig.14 Static Drain - Source On - State Resistance vs. Junction Temperature



10

0.01

## •Electrical characteristic curves

Resistance vs. Drain Current(I) 10000 Static Drain - Source On-State Resistance  $V_{GS} = 10V$ 1000 :  $R_{\text{DS(on)}}\left[\text{m}\Omega\right]$ T<sub>a</sub>=125°C T<sub>a</sub>=75°C 100

Fig.15 Static Drain - Source On - State

Drain Current : I<sub>D</sub> [A]

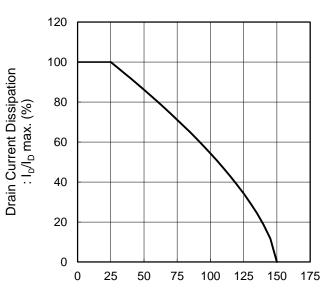
0.1

T<sub>a</sub>=25°C \_= -25°C

1

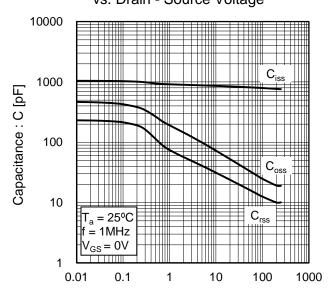
10

Fig.16 Drain Current Derating Curve



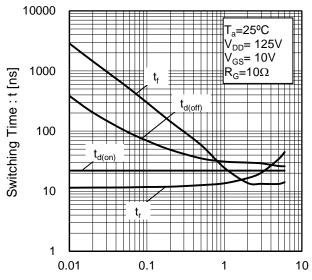
Junction Temperature : T<sub>i</sub> [°C]

Fig.17 Typical Capacitance vs. Drain - Source Voltage



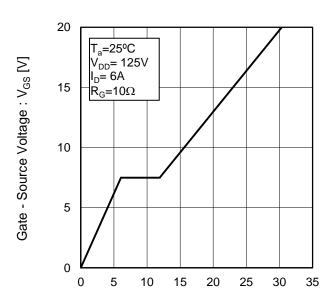
Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.18 Switching Characteristics

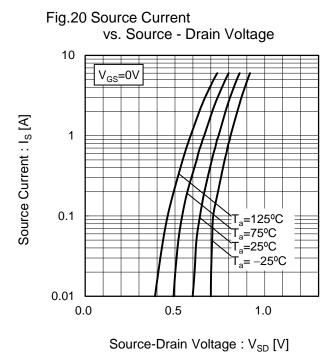


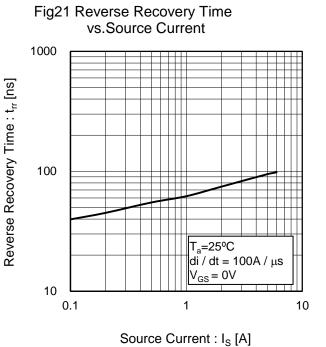
Drain Current : I<sub>D</sub> [A]

Fig.19 Dynamic Input Characteristics



Total Gate Charge : Q<sub>g</sub> [nC]





## ●Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

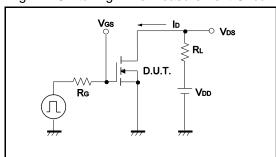


Fig.2-1 Gate Charge Measurement Circuit

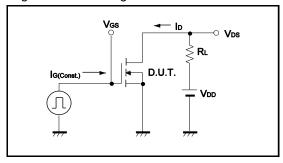


Fig.3-1 Avalanche Measurement Circuit

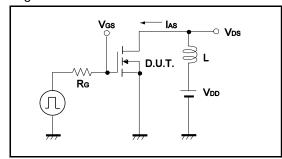


Fig.1-2 Switching Waveforms

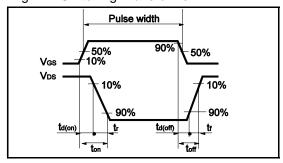


Fig.2-2 Gate Charge Waveform

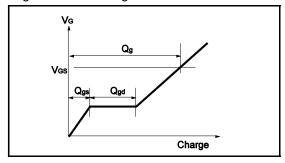
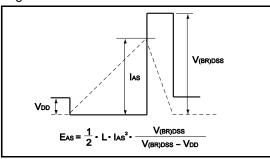
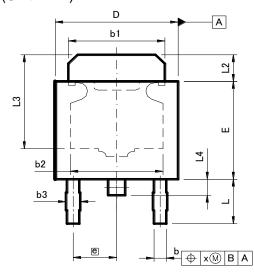


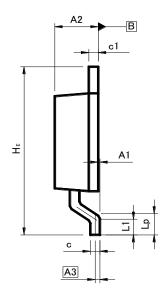
Fig.3-2 Avalanche Waveform

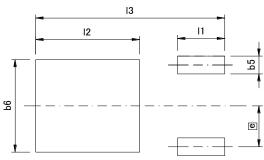


# ● **Dimensions** (Unit: mm)









DIM	MILIM	ETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
A1	0.00	0.15	0	0.006	
A2	2.20	2.50	0.087	0.098	
A3	0.3	25	0.0	01	
b	0.55	0.75	0.022	0.03	
b1	5.00	5.30	0.197	0.209	
b2	5.0	00	0.2	20	
b3	0.	75	0.03		
С	0.40	0.60	0.016	0.024	
c1	0.40	0.60	0.016	0.024	
D	6.30	6.70	0.248	0.264	
E	5.40	5.80	0.213	0.228	
е	2.	30	0.09		
HE	9.00	10.00	0.354	0.394	
L	2.20	2.80	0.087	0.11	
L1	0.80	1.40	0.031	0.055	
L2	1.20	1.80	0.047	0.071	
L3	5.30		0.209		
L4	0.9	90	0.0	35	
Lp	1.00	1.60	0.039	0.063	
Х	_	0.25	_	0.01	

DIM	MILIM	ETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
b5	_	1.00	-	0.04	
b6	_	5.20	-	0.205	
I1	_	2.50	-	0.098	
12	_	5.50	-	0.217	
13	_	10.00	_	0.394	

Dimension in mm/inches

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Γ	CLASSIV	CLASSⅢ	CLASSⅢ	CLASSⅢ

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  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
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- 7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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  - [d] the Products are exposed to high Electrostatic
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